

3A, 50V - 1000V High Efficient Surface Mount Rectifier

FEATURES

- Low power loss, high efficiency
- Low forward voltage drop
- Low profile package
- · Fast switching for high efficiency
- Ideal for automated placement
- Glass passivated chip junction
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APP	LICAT	IONS
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- Switching mode power supply (SMPS)
- Adapters
- Monitor
- TV

MECHANICAL DATA

- Case: DO-214AA (SMB)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.093g (approximately)

KEY PARAMETERS					
PARAMETER	VALUE	UNIT			
I _F	3	Α			
V_{RRM}	50 - 1000	V			
I _{FSM}	100	Α			
T _{J MAX}	150	°C			
Package	DO-214AA (SMB)				
Configuration	Single die				





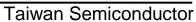




DO-214AA (SMB)



ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)										
PARAMETER	SYMBOL	HS 3AB	HS 3BB	HS 3DB	HS 3FB	HS 3GB	HS 3JB	HS 3KB	HS 3MB	UNIT
Marking code on the device		HS 3AB	HS 3BB	HS 3DB	HS 3FB	HS 3GB	HS 3JB	HS 3KB	HS 3MB	
Repetitive peak reverse voltage	V_{RRM}	50	100	200	300	400	600	800	1000	V
Reverse voltage, total rms value	$V_{R(RMS)}$	35	70	140	210	280	420	560	700	V
Forward current	I _F				;	3				Α
Surge peak forward current 8.3ms single half sine-wave superimposed I _{FSM} 100 on rated load			А							
Junction temperature	T _J - 55 to +150			°C						
Storage temperature	T _{STG} - 55 to +150			°C						





THERMAL PERFORMANCE					
PARAMETER	SYMBOL	TYP	UNIT		
Junction-to-ambient thermal resistance	R _{eJA}	60	°C/W		

PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
(1)	HS3AB HS3BB HS3DB HS3FB		V	-	1.0	V
Forward voltage ⁽¹⁾	HS3GB	-	V_{F}	-	1.3	V
	HS3JB HS3KB HS3MB			-	1.7	V
Reverse current @ rated V _R ⁽²⁾		T _J = 25°C		-	10	μA
		T _J = 100°C	- I _R	-	250	μA
Junction capacitance	tion capacitance HS3AB HS3BB HS3DB HS3FB HS3FB HS3GB 1MHz, V _R = 4.0V C _J		C _J	80	-	pF
	HS3JB HS3KB HS3MB			50	-	pF
Reverse recovery time	HS3AB HS3BB HS3DB HS3FB HS3GB	$I_F = 0.5A, I_R = 1.0A,$ $I_{rr} = 0.25A$	t _{rr}	-	50	ns
	HS3JB HS3KB HS3MB			-	75	ns

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION		
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING
HS3xB	DO-214AA (SMB)	3,000 / Tape & Reel

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Notes:

1. "x" defines voltage from 50V(HS3AB) to 1000V(HS3MB)



CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

Fig.1 Forward Current Derating Curve

A VERAGE FORWARD CURRENT (°C)

4 (W)

A VERAGE FORWARD CURRENT (°C)

A VERAGE FOR MARD CURRENT (°C)

Fig.2 Typical Junction Capacitance

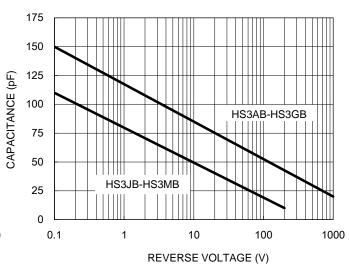


Fig.3 Typical Reverse Characteristics

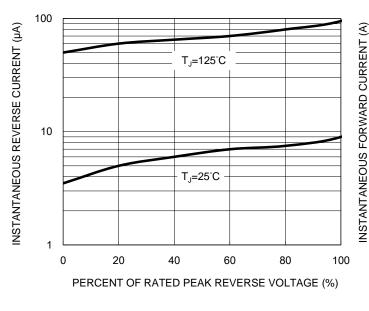
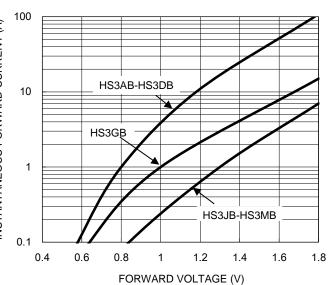


Fig.4 Typical Forward Characteristics



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CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

Fig.5 Maximum Non-Repetitive Forward Surge Current

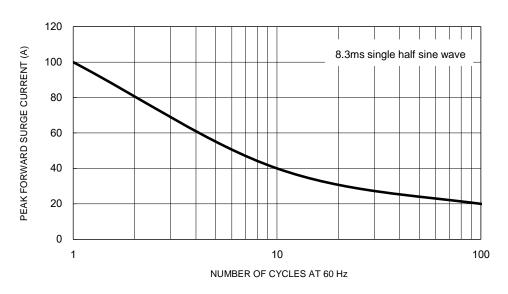
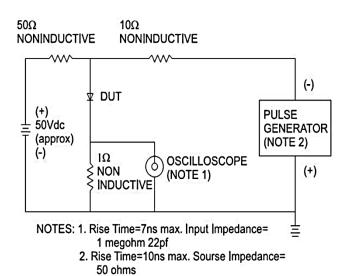
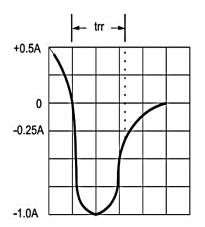


Fig.6 Reverse Recovery Time Characteristic and Test Circuit Diagram

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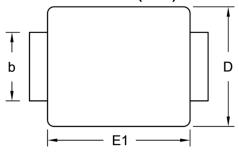
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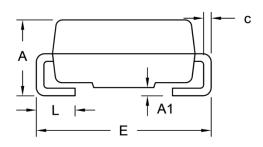




PACKAGE OUTLINE DIMENSIONS

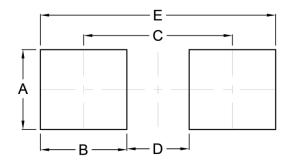
DO-214AA (SMB)





DIM	DIM. Unit (mm)		Unit (inch)		
Dilvi.	Min.	Max.	Min.	Max.	
Α	1.95	2.65	0.077	0.104	
A1	0.05	0.20	0.002	0.008	
b	1.95	2.20	0.077	0.087	
С	0.15	0.31	0.006	0.012	
D	3.30	3.95	0.130	0.156	
E	5.10	5.60	0.201	0.220	
E1	4.05	4.60	0.159	0.181	
L	0.75	1.60	0.030	0.063	

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
Α	2.30	0.091
В	2.50	0.098
С	4.30	0.169
D	1.80	0.071
E	6.80	0.268

MARKING DIAGRAM



P/N = Marking Code G = Green Compound

= Date Code ΥW F = Factory Code

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